



1. Material
  - 1.1. All material to be RoHS compliant.
  - 1.2. All material to be tolerant of Pb-free solder process temperatures.
  - 1.3. All material, including solder mask and legends, shall have a UL flammability rating of 94V-0. Date code and manufacturers UL symbol/type shall be permanently marked or etched on the board.
  - 1.4. Finish: ENIG.
2. Solder Mask
  - 2.1. Solder mask both sides, with blue color.
  - 2.2. Encroach primary side via pads but prevent solder mask in via holes.
  - 2.3. No solder mask on secondary side via pads.
  - 2.4. No solder mask on component pads
  - 2.5. Solder mask must be present between adjacent SMT pads.
3. Silkscreen
  - 3.1. No silkscreen allowed on exposed lands or in holes.
4. Dimensions
  - 4.1. Overall Thickness: .062" +/- 10%
  - 4.2. Hole tolerance +/- .005"

LAYER-STACK	Sym	Nº	Mils	MM	Qty	Plated
01-16	+	1	24	0.60	83	YES
01-20	×	2	32	0.81	8	YES
	▣	3	40	1.02	142	YES
	◇	4	51	1.30	4	YES
	⊗	5	67	1.70	2	YES
	⊗	6	125	3.18	2	NOT